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CUSTOMER . CUS999

SAMPLE CODE . SH240320T-037-L09Q

MASS PRODUCTION CODE . PH240320T-037-L09Q

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 001

DRAWING NO. (Ver.) . JLMD- PH240320T-037-L09Q (Ver.001)

PACKAGING NO. (Ver.) .

Customer Approved

Date:



Approved	Checked	Designer
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- Preliminary specification for design input
- ☐ Specification for sample approval

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History of Version

Date	Ver.	Edi.	Description	Page	Design by
9/2/2009	01	001	New Drawing	•	Bob
		X			

Total: 25 Page



Contents

1. SPECIFICATIONS

- 1.1 Features
- 1.2 Mechanical Specifications
- 1.3 Absolute Maximum Ratings
- 1.4 DC Electrical Characteristics
- 1.5 Optical Characteristics
- 1.6 Backlight & LED Characteristics

2. MODULE STRUCTURE

- 2.1 Counter Drawing
- 2.2 Interface Pin Description
- 2.3 Timing Characteristics

3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart
- 3.2 Inspection Specification

4. RELIABILITY TEST

4.1 Reliability Test Condition

5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

Appendix: LCM Drawing



1. SPECIFICATIONS

1.1 Features

Main LCD Panel

Item	Standard Value
Display Type	240 * (R · G · B) * 320 Dots
LCD Type	a-Si TFT , Normally white TN mode , Transmissive
Screen size(inch)	2.8 (Diagonal)
Viewing Direction	12 O'clock
Color configuration	R.G.B. vertical stripe
Backlight	White LED
Interface	8/16-bit 80-system I/F
Driver IC	R61580
	THIS PRODUCT CONFORMS THE ROHS OF PTC
ROHS	Detail information please refer web side :
	http://www.powertip.com.tw/news/LatestNews.asp

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	50.0 (W) * 69.2 (L) * 3.05 (H)(Max.)	mm

LCD Panel

Item	Standard Value			
Viewing Area	44.8 (W) * 59.2 (L)	mm		
Active Area	43.2(W) * 57.6 (L)	mm		

Note: For detailed information please refer to LCM drawing



1.3 Absolute Maximum Ratings

Module

Item	Symbol Condition		Min.	Max.	Unit
Power Supply Voltage	VCC -		-0.3	+4.6	V
System Dower Supply Voltage	VGH-VGL		-0.3	+30.0	V
System Power Supply Voltage	GND-VGL	-	-18.5	+13.0	V
Input Voltage	VIN	-	-0.3	VCC +0.3	V
Operating Temperature	T _{OP}	-	-20	+70	°C
Storage Temperature	T _{ST}		-30	+80	°C
Storage Humidity	H_D	Ta < 40 °C	20	90	%RH

1.4 DC Electrical Characteristics

Module GND = 0V, Ta = $25^{\circ}C$

					,	
Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VCC	·		3.3	-	>
Input High Voltage	V _{IH}		0.8*VCC	-	VCC	V
Input Low Voltage	V _{IL}	·	-0.3	-	0.2* VCC	V
Output High Voltage	V _{OH}	IOH = -0.1mA	0.8*VCC		-	V
Output Low Voltage	V _{OL}	IOL = 0.1mA	-	ı	0.2* VCC	V
Supply Current	ICC	VCC =3.3V, Pattern=Full display *1	TBD	TBD	TBD	mA

Note1:Maximum current display



1.5 Optical Characteristics

TFT LCD Panel

VCC =3.3V, Ta=25°C

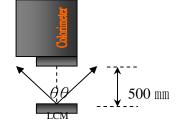
				1				
Item		Symbol	Condition	Min.	Тур.	Max.	unit	
Response tin	Response time		Ta = 25° C θ X, θ Y = 0°	-	45	68	ms	Note2
	Тор	θΥ+		-	50	1		
Viewing angle	Bottom	θΥ-	θY- CR ≥ 10	-	45	ı	Deg.	Note4
viewing angle	Left	θX-	CIV 2 10	-	50	1	Deg.	NOIG4
	Right	θΧ+		-	50	1		
Contrast rati	0	CR	CR		TBD	TBD	-	Note3
	White	Χ		TBD	TBD	TBD		
	VVIIILE	Y		TBD	TBD	TBD		
0 1 (0)5	Red	Dod X T	Ta = 25°C	TBD	TBD	TBD		
Color of CIE Coordinate	Reu	Υ		TBD	TBD	TBD		Note1
(With B/L)	Green	Χ	θX , $\theta Y = 0^{\circ}$	TBD	TBD	TBD	_	NOLET
(**************************************	Green	Υ		TBD	TBD	TBD		
	Blue	Х		TBD	TBD	TBD		
	Diue	Y		TBD	TBD	TBD		
Average Brightr	ness							
Pattern= white		IV	IF= 80mA	TBD	TBD	TBD	cd/m ²	Note1
(With B/L)								

Note1:

- 1 : △B=B(min) / B(max) ×100% 2 : Measurement Condition for Optical Characteristics: a : Environment: 25°C±5°C / 60±20%R.H · no wind · dark room below 10 Lux at typical lamp current and typical operating frequency. b : Measurement Distance: $500 \pm 50 \text{ mm}$, $(\theta=0^\circ)$ c : Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation.

 - d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





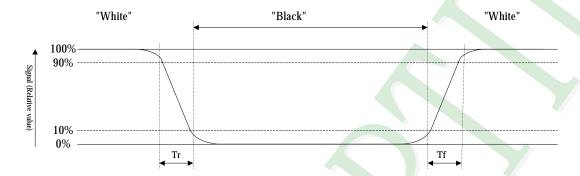
Colorimeter=BM-7 fast



Note2: Definition of response time:

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:



Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

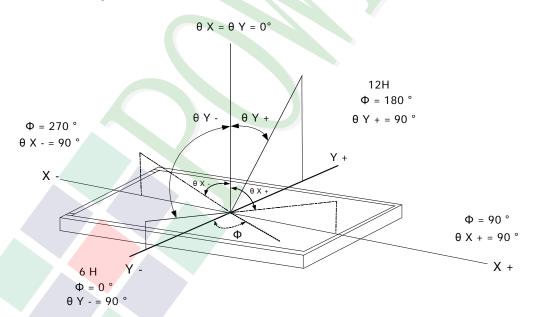
Photo detector output when LCD is at "White" state

Contrast ratio (CR) =

Photo detector output when LCD is at "Black" state

Note4: Definition of viewing angle:

Refer to figure as below:





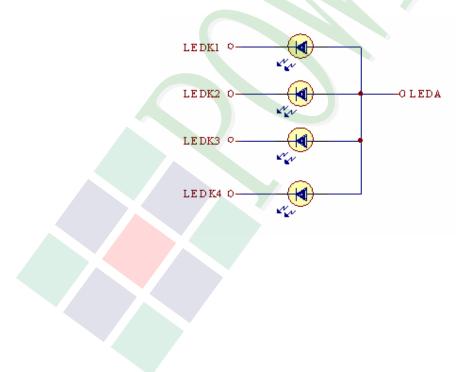
1.6 Backlight & LED Characteristics

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°C	-	120	mA
Reverse Voltage	VR	Ta =25°℃	-	5	V
Power Dissipation	PD	Ta =25°℃	-	430	mW

Electrical / Optical Characteristics

Electrical / Optical Characteriolics						
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF		-	3.3	-	V
Average Brightness (without LCD)	IV	IF= 80mA	250	300	-	cd/m ²
Color of CIE Coordinate	X		0.26	0.28	0.32	
(without LCD)	Y		0.26	0.28	0.32	=
Color			White			





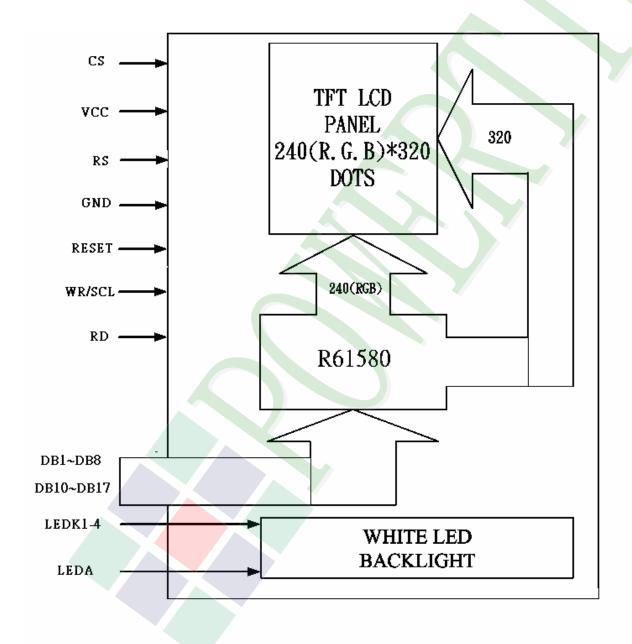
2. MODULE STRUCTURE

2.1 Counter Drawing

2.1.1 LCM Mechanical Diagram

* See Appendix

2.1.2 Block Diagram





2.2 Interface Pin Description

Pin No.	Symbol	Function
1	LEDK1-4	Power supply for LED Backlight Cathode input
2	3.3V/LEDA	Power supply for LED Backlight Anode input
3	GND	Signal ground.(0V)
4	RESET	Reset input pin for TFT LCD. When RESET is "L", initialization is executed.
5	DB17	
6	DB16	
7	DB15	
8	DB14	
9	DB13	
10	DB12	
11	DB11	
12	DB10	Bi-directional data bus
13	DB8	Di-uli ectional data bus
14	DB7	
15	DB6	
16	DB5	
17	DB4	
18	DB3	
19	DB2	
20	DB1	
21	RD	Read signal input, active at Low.
22	WR/SCL	Write signal input, active at Low.
23	RS	When RS = 0: Command. When RS = 1: Display data.
24	CS	Chip select signal , Active at "L"
25	XR/X+	NC



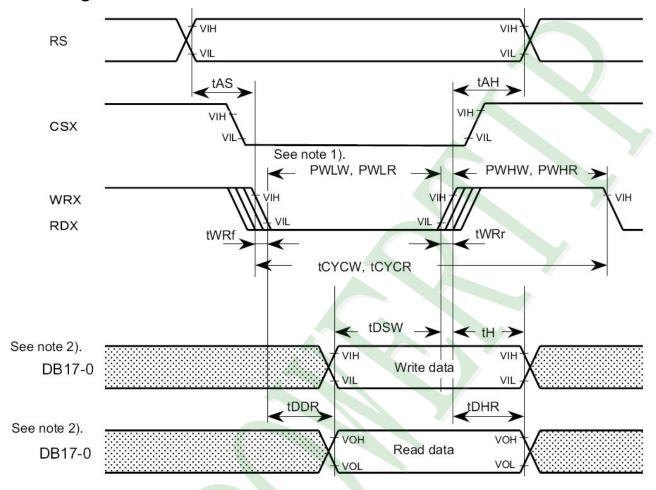
Pin No.	Symbol	Function
26	YD/Y-	
27	XL/X-	NC
28	YU/Y+	
29	GND	Signal ground.(0V)
30	3.3/VCC	Power supply for the internal logic circuit.



PH240320T-037-L09Q Page11 SAMPLE Ver. 01 SPEC Edi.001



2.3 Timing Characteristics



Note 1) PWLW and PWLR are defined by the overlap period when CSX is "low" and WRX or RDX is "low". Note 2) Unused DB pins must be fixed at "IOVCC" or "GND".



80-System Bus Interface Timing Characteristics (8-bit Interface)

Item		Symbol	Unit	Timing Diagram	Min.	Тур.	Max.
Bus cycle time	Write	tcycw	ns	Figure A	70	- /	_
	Read	tcycr	ns	Figure A	450	- (-
Write low-level pu	ulse width	PWLW	ns	Figure A	30		-
Read low-level po	ulse width	PWLR	ns	Figure A	170	7-4	
Write high-level p	oulse width	PWHW	ns	Figure A	25	-	_
Read high-level p	oulse width	PWHR	ns	Figure A	250	-	-
Write / Read rise	fall time	twRr, WRf	ns	Figure A	70	_	25
Setup time	Write (RS to CSX, WRX)	tas	ns	Figure A	0	-	-
	Read (RS to CSX, RDX)	tas	ns	Figure A	10	-	->
Address hold time	e	tah	ns	Figure A	2	_	44
Write data setup	time	tosw	ns	Figure A	25	-	_
Write data hold time		tH	ns	Figure A	10	//	_
Read data delay time		tDDR	ns	Figure A			150
Read data hold ti	me	tDHR	ns	Figure A	5	7-	_

Note: The above values are target values. They are subject to change.

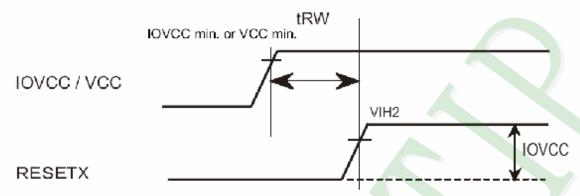
80-System Bus Interface Timing Characteristics (16-bit Interface)

Item		Symbol	Unit	Timing Diagram	Min.	Тур.	Max.
Bus cycle time	Write	tcycw	ns	Figure A	75	-	-
	Read	tcycr	ns	Figure A	450	-	-
Write low-level pul	lse width	PWLW	ns	Figure A	40	-	-
Read low-level pu	Ise width	PWLR	ns	Figure A	170	-	-
Write high-level pu	ulse width	PWHW	ns	Figure A	25	-	-
Read high-level pu	ulse width	PWHR	ns	Figure A	250	-	-
Write / Read rise/	fall time	twr, wrf	ns	Figure A	-	-	25
Setup time	Write (RS to CSX, WRX)	440	ns	Figure A	0	-	-
	Read (RS to CSX, RDX)	- tas	ns	Figure A	10	-	-
Address hold time		tan	ns	Figure A	2	-	-
Write data setup ti	me	tosw	ns	Figure A	25	-	-
Write data hold tin	ne	tH	ns	Figure A	10	-	-
Read data delay ti	me	tddr	ns	Figure A	-	-	150
Read data hold tin	ne	tDHR	ns	Figure A	5	-	-

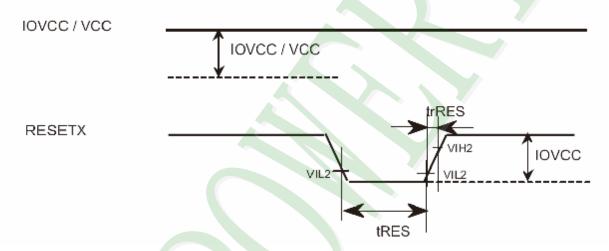
Note: The above values are target values. They are subject to change.



Reset timing when power supply is input



Reset timing during normal operation



Reset Timing Characteristics

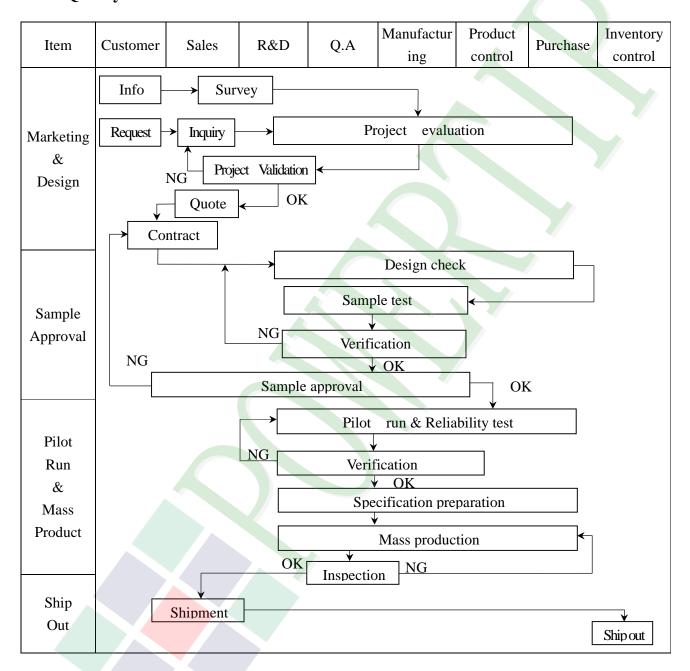
Item	Symbol	Unit	Timing Diagram	Min.	Тур.	Max.
Reset wait time	trw	ms	Figure C-1	1	_	_
Reset low-level width	tres	ms	Figure C-2	1	_	_
Reset rise time	trRES	μs	Figure C-2	_	_	10

Note: The above values are target values. They are subject to change.

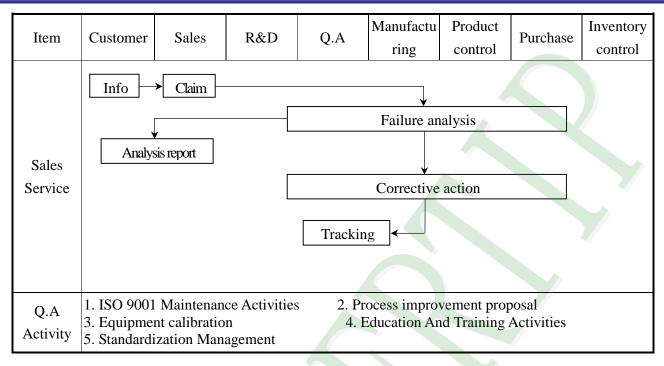


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

◆Scope : The document shall be applied to TFT-LCD Module for less than 3.5" (Ver.02).

◆Inspection Standard: MIL-STD-105E Table Normal Inspection Single Sampling Level Ⅱ.

◆Equipment : Gauge · MIL-STD · Powertip Tester · Sample

◆Defect Level: Major Defect AQL: 0.4; Minor Defect AQL: 1.5

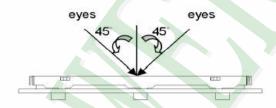
♦OUT Going Defect Level: Sampling.

◆Standard of the product appearance test:

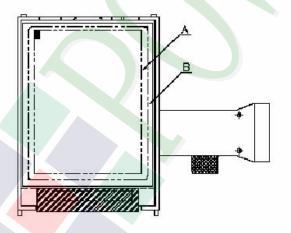
a. Manner of appearance test:

(1). The test best be under 20W×2 fluorescent light, and distance of view must be at 30 cm.

(2). The test direction is base on about around 45° of vertical line.



(3). Definition of area.



A area: viewing area

B area: Outside of viewing area

(4). Standard of inspection: (Unit: mm)



◆Specification For TFT-LCD Module Less Than 3.5″:

NO	Item	Criterion (Level			
		1. 1The part number is inconsistent with work order of production.				
01	Product condition	1. 2 Mixed product types.	Major			
		1. 3 Assembled in inverse direction.	Major			
02	Quantity	2. 1The quantity is inconsistent with work order of production.	Major			
03	Outline dimension	3. 1 Product dimension and structure must conform to structure diagram.	Major			
		4. 1 Missing line character and icon.	Major			
	04 Electrical Testing	4. 2 No function or no display.				
04		4. 3 Display malfunction.				
		4. 4 LCD viewing angle defect.				
		4. 5 Current consumption exceeds product specifications.	Major			
		Item Acceptance (Q'ty)				
	Dot defect	Bright Dot ≤ 2				
	Dot delect	Dot Dark Dot ≤ 3				
	(Bright dot \	Defect Joint Dot ≤ 2				
05	Dark dot)	Total ≤ 3	Minor			
	On -display	5. 1 Inspection pattern: full white, full black, Red, Green and				
		blue screens.				
		5. 2 It is defined as dot defect if defect area $>1/2$ dot.				
		5. 3 The distance between two dot defect ≥ 5 mm.				



♦Speci	ification For TFT-LCD M	Iodule Less Than 3, 5":			(Ver. 02)
NO	Item	Crit	terion		Level
		6. 1 Round type (Non-display	or display	9):	
		Dimension (diameter : Φ)	Acce	eptance (Q'ty)	
	Black or white	$\Phi \leq 0.15$		Ignore	
	dot \ scratch \ contamination	$0.15 < \Phi \leq 0.20$		2	
	Round type	$0.20 < \Phi \leq 0.30$		2	
	→ <u>x</u> ← ↓	Ф > 0.30		0	
	Y	Total		3	
06	T				Minor
	$\Phi = (x+y)/2$	6, 2 Line type(Non-display or	display) :		
	Line type	Length (L) Width (W)	Acceptance (Q'ty)	
	V ¥w	W	≤ 0.03	Ignore	
	→ _L	$L \le 5.0$ 0.03 < W	≤ 0. 05	3	
		w	>0.05	As round type	
		Total		3	
		Dimension (diameter : Φ)	Acc	eptance (Q'ty)	
		$\Phi \leq 0.20$		Ignore	
07	Polarizer	$0.20 < \Phi \leq 0.50$		3	Minor
01	Bubble	Φ > 0.50		0	Millor
		Total		3	



◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion		Level
		Z: The thickness of crack	Y : The width of crack. W : terminal length a : LCD side length	
		8.1 General glass chip: 8.1.1 Chip on panel surface and cra	ack between panels:	
08	The crack of glass	SP Y [OK]	SP [NG]	Minor
		Seal width	X	
		X Y ≤ a Crack can't enter viewing area	Z ≤1/2 t	
		≤ a Crack can't exceed the half of SP width.	$1/2 t < Z \leq 2 t$	



♦ Specification For TFT-LCD Module Less Than 3, 5'':

NO	Item	Criterion	Level
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass 8. 1. 2 Corner crack:	
08	The crack of glass	8. 2 Protrusion over terminal: 8. 2. 1 Chip on electrode pad: X X Y X W Y X	Minor



◆Specification For TFT-LCD Module Less Than 3, 5":

NO	Item	Criterion	Level
		Symbols: X: The length of crack Z: The thickness of crack t: The thickness of glass Y: The width of crack. W: terminal length a: LCD side length	
08	The crack of glass	8. 2. 2 Non-conductive portion: X	Minor
		$\begin{array}{ c c c c }\hline X & Y & Z \\ & \leq a & \leq 1/3 \text{ W} & \leq t \\ \hline \end{array}$	



◆Specification For TFT-LCD Module Less Than 3.5":

NO	Item	Criterion	Level
		9. 1 Backlight can't work normally.	Major
09	09 Backlight elements	9, 2 Backlight doesn't light or color is wrong.	Major
		9, 3 Illumination source flickers when lit.	Major
		10. 1 Pin type \quantity \quantity \dimension must match type in structure diagram.	Major
	o General	10,2 No short circuits in components on PCB or FPC .	Major
10		10. 3 Parts on PCB or FPC must be the same as on the production characteristic chart .There should be no wrong parts , missing parts or excess parts.	Major
10	appearance	10. 4 Product packaging must the same as specified on packaging specification sheet.	Minor
		10.5 The folding and peeled off in polarizer are not acceptable.	Minor
		10. 6 The PCB or FPC between B/L assembled distance(PCB or FPC) is ≤ 1.5 mm.	Minor



4. RELIABILITY TEST

4.1 Reliability Test Condition

TEST ITEM	TES	ST CONDITION			
High Temperature Storage Test	Keep in +80 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
Low Temperature Storage Test	Keep in -30 ±2℃ 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
High Temperature / High Humidity Storage Test	Surrounding temperature, t	hen storage at normal condition 4hrs.			
ESD Test	 Temperature ambiance: Humidity relative:30% Energy Storage Capacita Discharge Resistance(Resistance) Discharge, mode of oper Single Discharge (time betw 	15°C \sim 35°C \sim 60% ance(Cs+Cd):150pF±10% l):330 Ω ±10% ation: een successive discharges at least 1 s)			
Temperature Cycling Storage Test	(30mins) (30m	$\begin{array}{cccccccccccccccccccccccccccccccccccc$			
Vibration Test (Packaged)	2. The amplitude of vibration	on :1.5 mm			
Drop Test (Packaged)	0 ~ 45 45.4 ~ 90	5.4 122 0.8 76 54 61			
	High Temperature Storage Test Low Temperature Storage Test High Temperature / High Humidity Storage Test ESD Test Temperature Cycling Storage Test Vibration Test (Packaged)	High Temperature Storage Test Low Temperature Storage Test High Temperature / High Humidity Storage Test ESD Tes			



5. PRECAUTION RELATING PRODUCT HANDLING

5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25°C ± 5°C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period
 - The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility
 - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.

